

EPDM30

Two-Part Thermal Conductive Adhesive

LiPOLY EPDM30 is a silicone-free two-part liquid gap filler, with high viscosity and good adhesion, it can be fast cured at room temperature or elevated temperature. With a thermal conductivity of 3.0 W/m*K, EPDM30 provides high thermal conductivity and low thermal impedance. It is ideally suited for dispensing using the dispensing robot or by syringe.

■ FEATURES

- / Thermal conductivity: 3.0 W/m*K
- / Can be applied with dispenser
- / Room Temperature curing or heating curing
- / Low compression stress during assembly
- / Excellent adhesion to metal & PCB

■ TYPICAL APPLICATION

- / Electronic components: IC、CPU、MOS、Mother Board、Wireless Hub
- Telecom Device、Automotive electronics、Computer and peripherals
- Between any heat-generating component and a heat sink.

■ CONFIGURATIONS

- / Cartridges: 50ml, 400ml
- / Other special and custom sizes are available upon request

■ PRESERVATION

It can be preserved for 60 months under the condition of unopened and under room temperature 25°C.

■ TYPICAL PROPERTIES

PROPERTY	EPDM30	TEST METHOD	UNIT
Color	White (A part) Black (B part)	Visual	-
Resin base	Epoxy	-	-
A:B	100:100	-	-
Viscosity A	270	DIN 53018	Pa.s
Viscosity B	330	DIN 53018	Pa.s
Density	2.8	ASTM D792	g/cm ³
Application temperature	-40~120	-	°C
Surface dry	25°C/50 min	By LiPOLY	-
Curing condition	25°C/4 hrs	By LiPOLY	-
Hardness	90	ASTM D2240	Shore A
Elongation at break	<1	ISO527	%
Tensile strength	60	ISO527	N/mm ²
Lap shear to aluminum	300	ASTM D1002	N/mm ²
Shelf life	60 months	-	-
ROHS & REACH	Compliant	-	-
ELECTRICAL			
Dielectric breakdown	14	ASTM D149	KV/mm
Volume resistivity	>10 ¹¹	ASTM D257	Ohm-m
THERMAL			
Thermal conductivity	3.0	ISO 22007-2	W/m*K

